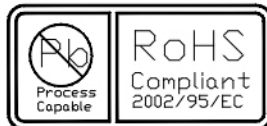
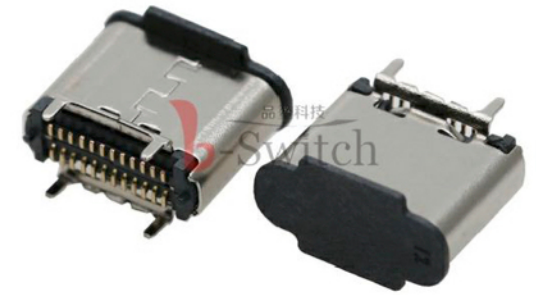
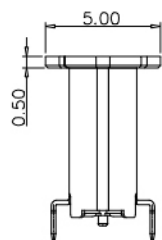
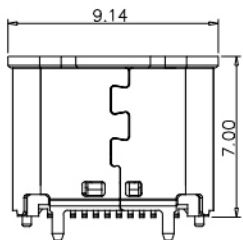


RECOMENDED PCB LAYOUT
PCB T=1.20mm
TOL:±0.05



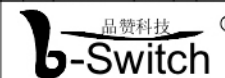
PIN DEFINE:

Pin	Signal Name	Description	Mating Sequence	Pin	Signal Name	Description	Mating Sequence
A1	DND	Ground return	First	B12	DND	Ground return	First
A2	SS1p1	Positive half of first SuperSpeed TX differential pair	Second	B11	SS1p1	Positive half of first SuperSpeed RX differential pair	Second
A3	SS1m1	Negative half of first SuperSpeed TX differential pair	Second	B10	SS1m1	Negative half of first SuperSpeed RX differential pair	Second
A4	Vbus	Bus Power	First	B9	Vbus	Bus Power	First
A5	CC1	Configuration Channel	Second	B8	SB12	Sideband Use(SBU)	Second
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	Second	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2	Second
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	Second	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2	Second
A8	SB11	Sideband Use(SBU)	Second	B5	CC2	Configuration Channel	Second
A9	Vbus	Bus Power	First	B4	Vbus	Bus Power	First
A10	SS1m2	Negative half of second SuperSpeed TX differential pair	Second	B3	SS1m2	Negative half of second SuperSpeed TX differential pair	Second
A11	SS1p2	Positive half of second SuperSpeed TX differential pair	Second	B2	SS1p2	Positive half of second SuperSpeed TX differential pair	Second
A12	DND	Ground return	First	B1	DND	Ground return	First



NOTE:

- MATERIAL SPECIFICATION:
 - HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, WITH 30% GLASS FILLED, UL94 V-0 BLACK.
 - CONTACTS: COPPER ALLOY
 - EMI SPRING: STAINLESS STEEL
 - FRONT SHELL: STAINLESS STEEL
 - MIDDLE BLADE: STAINLESS STEEL
- PLATING SPECIFICATION:
 - CONTACTS:
 - NI 50µ" MIN. UNDER PLATED OVER ALL.
 - 1-30µ" Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. TIN PLATED ON SOLDER AREA.
 - EMI SPRING: CLEANING ONLY
 - FRONT SHELL:
 - NI 50µ" MIN. UNDER PLATED OVER ALL.
 - MIDDLE BLADE:
 - NI 50µ" MIN. UNDER PLATED OVER ALL.
- MECHANICAL PERFORMANCE,
 - INSERTION FORCE: 0.5-2.0kgf.
 - REMOVAL FORCE: 0.8kgf-2.0kgf.
 - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,
 - CURRENT RATING: 5.0A VOLTAGE RATING: 5.0V
 - LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX. SHIELD: 50mA/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mA
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE: AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C+85°C.
- IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



G-Switch Electronic (HongKong) CO.,Ltd.

Unless otherwise specified, Tolerance:
 X. ±0.30
 X.x ±0.20
 X.xx ±0.15
 X.xxx ±0.10
 Angles ±3°

DESIGN: FengFengChen
 CHECKED: DATE
 APPROVED: DATE
<http://www.dg-switch.com>
 TEL: 0769-82388879

DATE: 2019.05.29
 DATE
 DATE
 REV.: X1
 SIZE: A4

Molde code:
GT-USB-7052
 SCALE: 4:1
 SHEET: 1/1
 UNIT: mm